

1 Introduction

The LPC5411x are Arm® Cortex® -M4 based microcontrollers for embedded applications. These devices include:

- an optional Arm Cortex-M0+ coprocessor
- up to 192 KB of on-chip SRAM
- up to 256 KB on-chip flash

Over-The-Air (OTA) is a procedure to update the firmware without using physical wires. OTA is a solution for the current **LPC54114 BLE Audio System**. When a product is ready and released in the field, OTA can be used to upload new firmware that brings new features.

- For a customer, OTA is convenient because the Headset does not need to be connected to a PC.
- For a manufacturer, OTA reduces the BOM cost as no USB hardware needs to be present.

This document provides **OTA Operation Steps** to support firmware update in the memory of LPC54114 with the tools of **NXH3670_SDK_Gaming_G3.0**. For more specific OTA introductions including HAPI, Concept, refer to HAPI OTA.

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2 Concepts

2.1 OTA update process

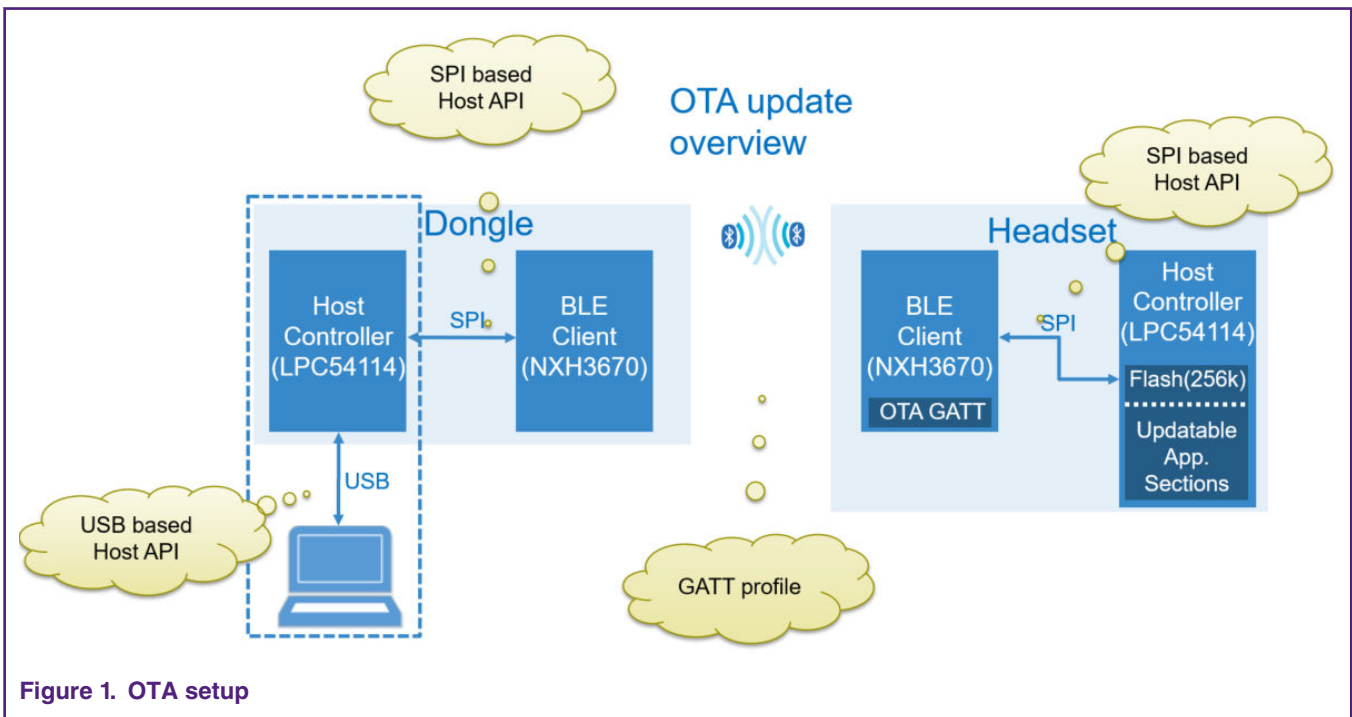


Figure 1. OTA setup



The setup requires a Dongle board, Headset board, PC and a USB cable. The USB cable is used to connect the Dongle and PC.

A typical scenario based on LPC54114 can be summarized as below:

1. Dongle and Headset are initially programmed over USB interface.
2. Dongle and Headset are paired.
 - Pairing Data (PD) of Headset is independent on the PD of Dongle.
Once the Headset is booted up, it retrieves PD from its own Memory that is written in advance and will not store extra PD.
 - PD of Dongle is dependent on the PD of Headset.
Once the Dongle is booted up, it retrieves PD and pair with Headset, and then stores the Headset device information in Dongle's PD section.
3. Dongle is re-flashed with the **OTA_Dongle** application, which is the start of the OTA process.
 - **OTA_Dongle** can be used as VCOM to transfer data between PC and LPC54114 through the USB.
 - Before re-flashing operation, make sure that the PD is not erased (Dongle is responsible for getting Headset's device information and **OTA_Dongle** is not). Two NXH devices are paired firstly and then connected, so they can't be connected if the user has erased PD data stored in Dongle's Flash.
 - In the **Debug mode**, the code takes up much space. The Headset does not have enough space to store **Headset** and **OTA_Headset** at the same time. So user can re-flash Headset with the **OTA_Headset** application to test OTA function.

NOTE

It is recommended to use the same `layout_release_sdk.yml` for both Headset and `OTA_Headset` demos. Only the application and NXH3670's binaries to Flash are required to be downloaded (the Partition table and init pairing_data are not required).

4. OTA process is triggered by PC application.
5. OTA finishes. The firmware of Headset is updated.
6. Re-flash the Dongle with Gaming application, which is the end of the OTA process.

2.2 SSB

The Second Stage Bootloader (SSB) is automatically bootstrapped by the (ROM) first stage bootloader.

You can store multiple firmware in Flash according to your requirements and inform SSB which firmware to boot.

For example, considering Headset board has no USB port in the **LPC54114 BLE Audio System**, developers store at least three firmware in advance, including

- SSB: to decide which firmware to boot
- OTA firmware: to receive new firmware
- application firmware: actual application, including specific Headset functions

Taking the current demos as an example, the following describes the functions of SSB:

1. Set the VTOR to the application vector table address.
2. Set stack pointers to the application stack pointer.
3. Jump to the application (PC now points to application).

NOTE

In the current design, the NXH3670 is used to transfer data over the air and program LPC54114 through the SPI interface with the SSB code.

Define `NO_CRP` to ensure that the program starts at the specified location, if using SSB to boot application (the ignoring of this step may result in the `0x02FC` offset in the application).

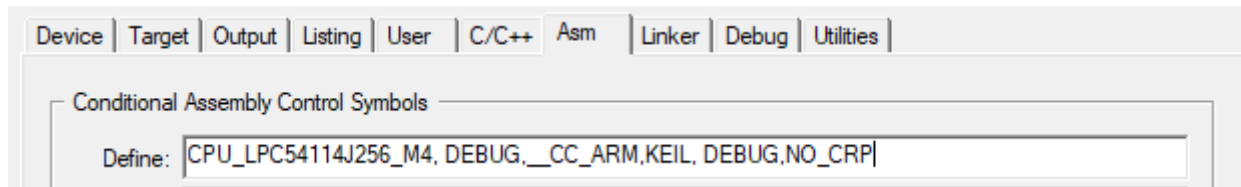


Figure 2. `NO_CRP` settings

2.3 Partition table

The Dongle, OTA_Dongle, Headset and OTA_Headset applications and their locations are required to be mapped in Flash. This mapping is present in the Partition Table stored at a fixed offset in the Flash memory of the Host controller. For more information, refer to HAPI OTA.

The followings are important to note:

1. The Sector size is different between LPC54114 and KL27.
 - LPC54114: 8 Sectors (0-7), and the size of per Sector is 32 KB.
 - KL27: 256 Sectors (0-255), and the size of per Sector is 1 KB.
2. The current software design of the OTA process contains the following three scenarios.
 - The **Active flag** of Partition Table and PD of Dongle is reassigned with new value to inform SSB which firmware to boot.
 - If the `KL_APP` is set to **Sector0 (0x00000000 – 0x0000 7FFF)**, the original data is copied to SRAM during OTA. You can change the data and then flush the changed data back to **Sector0** with FLASHIAP API.
 - The interrupted vectors are stored in **Sector0**.

All the data can be cleaned up when there is an unexpected power-off or other uncertainty reason.

Therefore, in the software design of LPC54114, **SSB** and `ota_app`, which will never be changed, are put on **Sector0** and **Partition Table** and **PD** on **Sector7**.

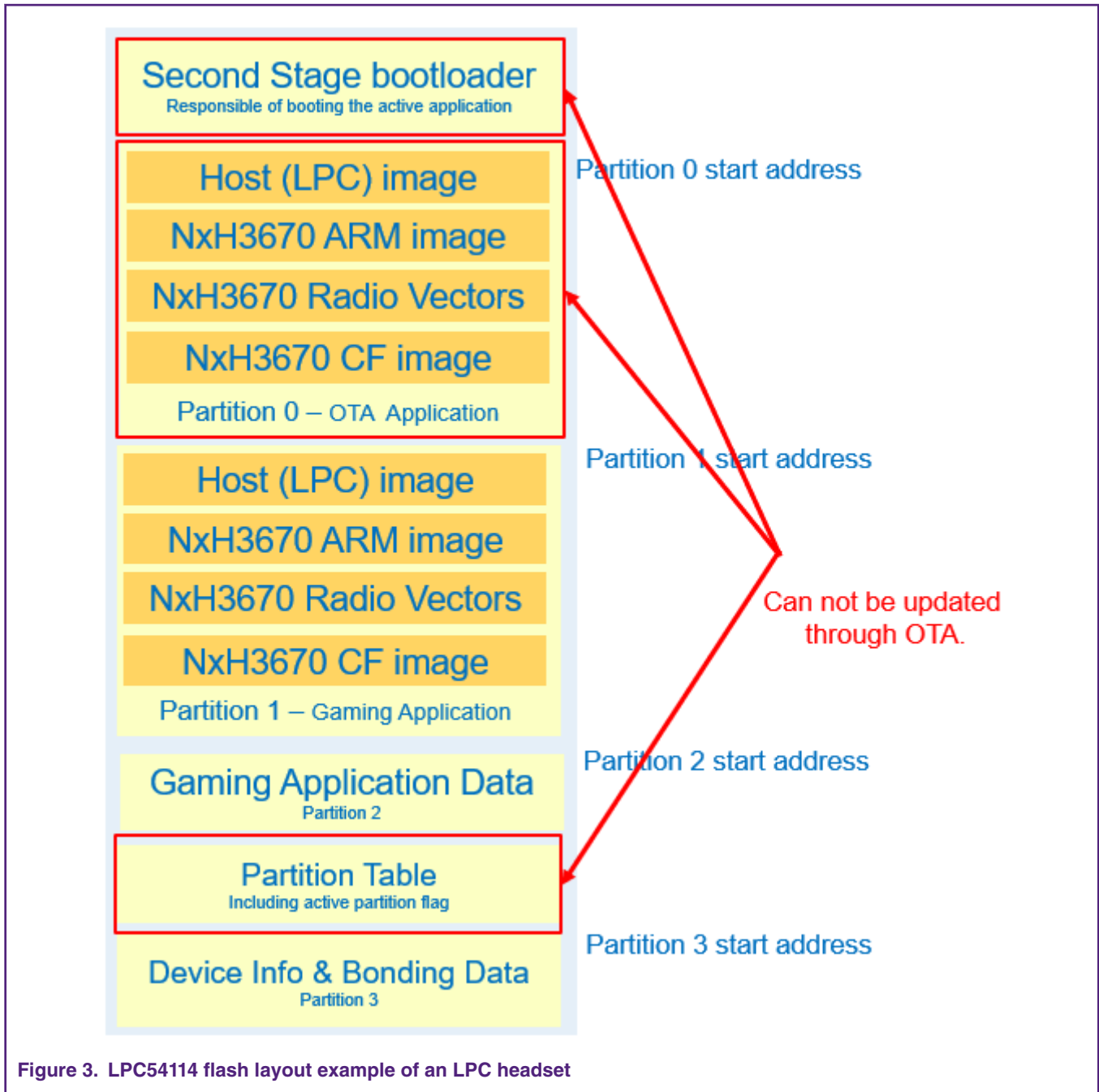


Figure 3. LPC54114 flash layout example of an LPC headset

- **Partition 0** is the OTA application, and it contains the Host Controller (LPC54114) firmware and NxH3670 Arm Image. For **OTA_Dongle**, only `ota_app` and `NxH_Binary (Arm.phOtaDongle.ihex.eep)` are required to be flashed.
 - `rfmac (rfmac.eep)` is added in the NxH image.
 - `CF (phStereoInterleavedAsrcTx.eep)` is not required or used.
- **Partition 1** is the Gaming Application, and it contains the firmware for the Host Controller (LPC54114) firmware, the NxH3670 Arm image, the NxH3670 Audio RadioVectors, and NxH3670 CoolFlux image.
- **Partition 2** contains Application data meant as general-purpose data storage for the Gaming application. Currently, **Partition 2** is not used.

- **Partition 3** contains the Device info and Bonding data. Device information contains BLE specific attributes that need to be present for the air interface to work. Bonding data makes sure that Dongle and Headset automatically reconnect. Bonding data is only relevant for the Dongle.

3 Using flashtool

This document lists the operation steps to use .BAT to update firmware easily and quickly. For more specific introduction of Flashtool, refer to the **HAPI OTA** and tools sections in NXH3670_SDK_Gaming_G3.0.

3.1 Modificataion

- ota_update_headset.bat

```

20 if [%1] == [] (
21     choice /C AS /N /M "Updating an ADK[A] or SDK[S] board for headset?"
22     if ERRORLEVEL 2 (
23         set FLASHLIST=%APP_DIR%script\flashlist_release_sdk.yml
24         set LAYOUT=%APP_DIR%script\layout_release_sdk.yml
25         goto USB_CONFIG_U
26     )
27     if [%1] == [sdk] (
28         set FLASHLIST=%APP_DIR%script\flashlist_release_sdk.yml
29         set LAYOUT=%APP_DIR%script\layout_release_sdk.yml
30         goto USB_CONFIG_C
31     )
32 )
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74 --partition 0 --activate 0 --flash-only nxh_app,rfmac,cf,kl_app -v

```

flashlist_release_sdk.yml User need replace 'flashlist_release_sdk.yml' with their own 'flashlist_xxx.yml'
layout_release_sdk.yml User need replace 'layout_release_sdk.yml' with their own 'layout xxx.yml'
0 User can choose update which Partition over the air (Partition X)
0 User can choose activate which partition after over the air update (Active X)
nxh_app,rfmac,cf,kl_app User can choose which images to update

Figure 4. Modifying ota_update_headset.bat

With JLink, how can we convert .yaml of Partition table to .BIN that will be download to Flash?

- Open a command line interface.
- Go to the NXH3670_SDK_Gaming_G3.0 folder.
- Run flash_scripts\flashtool.cmd -> dev table.bin -> connection export -> layout kinetis_democode\apps\kl_dongle\script\layout_debug_sdk.yml.

```

C:\k127\NXH3670_SDK_Gaming_G3.0>flash_scripts\flashtool.cmd --dev table.bin --connection export
--layout kinetis_democode\apps\kl_dongle\script\layout_debug_sdk.yml
#### creating partition table layout ...
+++ reading layout file (kinetis_democode\apps\kl_dongle\script\layout_debug_sdk.yml) ...
+++ flashing the layout ...

```

| | | | |
|-----------|----------|-----------------|------|
| table.bin | BIN File | 2019/5/13 16:51 | 3 KB |
|-----------|----------|-----------------|------|

Figure 5. Converting .yaml to .bin

However, first 2560 (0xa00) bytes of this table.bin are all 0x00. This document provides two methods.

- Make sure that `table.bin` is flashed before flashing the SSB located in `0x00`. Otherwise, the `table.bin` will overwrite the SSB. So for OTA, user have to port the `kl_ssb` application or flash SSB file as well.
- Or, you can delete 2560 (`0xA00`) bytes of this `table.bin` and then download the changed `table.bin` to Partition table address.(In our software, we put it to `0x3f400`).

2. `flashlist_release_sdk.yml`

```

1  binaries:
2      - name: ssb
3        files:
4          - kinetis_democode/apps/kl_ssb/sdk/release/kl_ssb_sdk.bin
5          address: 0x0
6      - name: kl_app
7        files:
8          - kinetis_democode/apps/kl_headset/sdk/release/kl_headset_sdk.bin.eep
9          offset_index: 0
10         partition: { name: "app", type: firmware }
11         headroom: -1

```

- User can replace 'kl_ssb_sdk.bin' with their own SSB.bin
- User can replace this location with their own location for firmware
- User can replace 'kl_headset_sdk.bin.eep' with their own '.EEP' file

Figure 6. Modifying `flashlist_release_sdk.yml`

`flashlist_release_sdk.yml` (`kl_headset`) lists the binaries and `offset_index` of Partition used to operate OTA. **Figure 6** shows the example to update `kl_headset_sdk.bin.eep` to `offset_index_0` in the current Partition.

3. `layout_release_sdk.yml`

```

7  # partition_id 0
8  - name: "app"
9  type: firmware
10 base address: 0xbf0
11 size: 0x2a000 # 168 KB
12 offsets:
13 - 0x0 # kl_app | 52 KB (21 KB free)
14 - 0xd010 # nxh_app | 65 KB (4 KB free)
15 - 0x1d410 # rfmac | 18 KB (2 KB free)
16 - 0x21c10 # cf | 32 KB (2 KB free)
17 # partition_id 1
18 - name: "ota"
19 type: firmware
20 base address: 0x2abf0
21 size: 0x14c00 # 83 KB
22 offsets:
23 - 0x0 # kl_ota_app | 24 KB
24 - 0x6010 # nxh_ota_app | 58 KB

```

- ▭ If user want put OTA related code in Partition0, they can replace 'app' with 'ota'
- ▭ Partition0's base_address
- ▭ The offsets of Images in Partition0 is based on base_address.
- ▭ Partition1's base_address should be equal to or bigger than the sum of Partition0's address and size.

Figure 7. Modifying layout_release_sdk.yml

You can design your own `layout_release_sdk.yml` to meet the use of Flash. In the software design, MCU reads NXH_Binaries from specified location and then transfer data to NXH3670 through the SPI interface. Make sure the design of Flash layout is correct.

How can we convert .BIN to .EEP used in OTA process?

Use the `...tools\to_eep.cmd` and type in `-i XXX.bin -o XXX.bin.eep`.

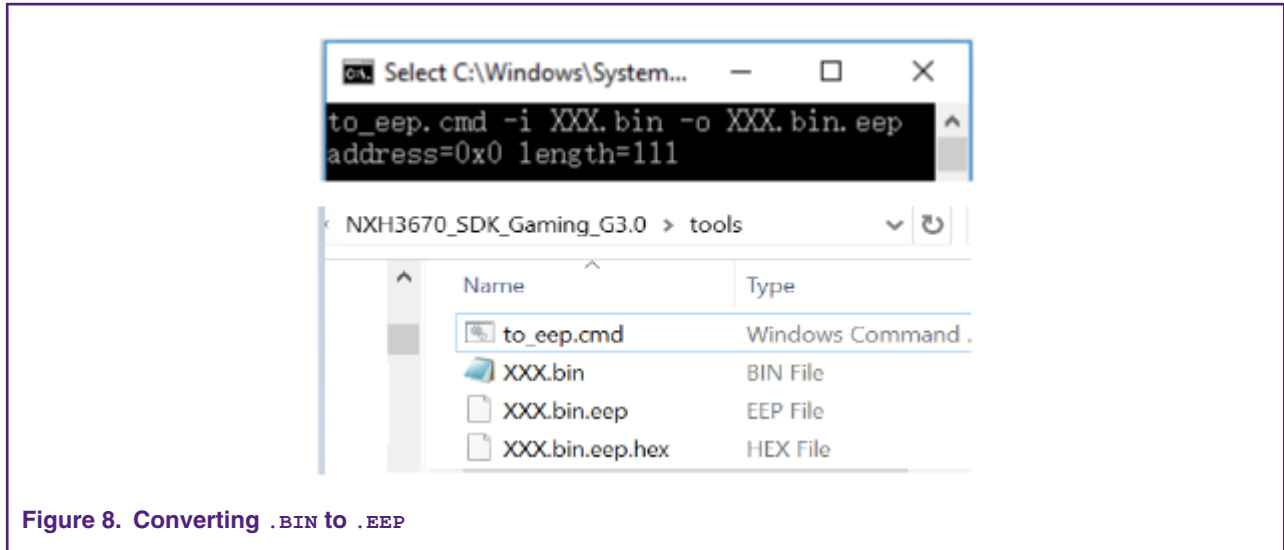


Figure 8. Converting .BIN to .EEP

The following two items are important;

- To keep ota Partition the first in memory, in the layout_release_sdk.yml file, keep in the order of ota, app, Without this order, a Partition Table.bin cannot be output or the Partition Table is not correct.
- Make sure that the addition value of base_address of Partition and its size is smaller than base_address of the next Partition.

3.2 Test process

After ota_update_headset.bat, flashlist_release_sdk.yml, and layout_release_sdk.yml are correctly modified, OTA can start.

This document lists steps when **Dongle** and **Headset** have been paired.

1. Download **OTA_Dongle** and make sure PC can recognize it as a **USB Serial Device**.

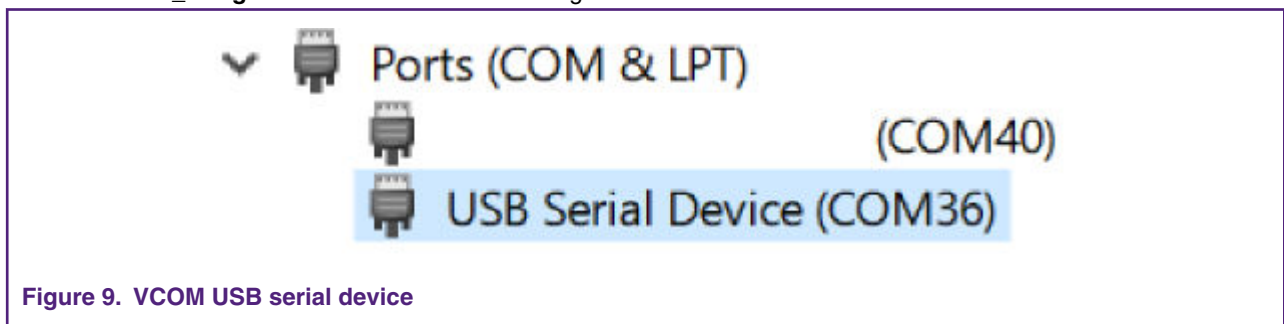


Figure 9. VCOM USB serial device

As shown in Figure 9, the PC recognizes it as **COM36**.

2. This document lists two cases.

- **Case 1:** app is running instead of ota_app.
 - In the **Release mode**, the Active_flag of APP_Partition is 1 (app), which indicates that userw need to send commandw to switch Active_Partition to OTA_Partition: 0 (ota_app).
 - In the **app case**, if phOtaHeadset.ihex.eep is used instead of phGamingRx.ihex.eep, it indicates that users have boot and start NXH3670 as OTA function (user can use OTA related tool to communicate with Dongle board with firmware phOtaHeadset.ihex.eep), and there is no need to switch remote Active_Partition. The hci_table of app do not have OTA related code, so it cannot be used for OTA .


```
##### flashing binaries ...
+++ reading flash list file ...
+++ checking flash list file ...
+++ connecting to the remote device ...
+++ switching remote active partition to OTA partition ...
+++ rebooting remote to OIA partition ...
+++ connecting to the remote device ...
+++ getting remote table version ...
```

Figure 10. switch operation

- **Case 2:** ota_app is running and NXH_Binary is phOtaHeadset.ihex.eep
 - In the **Debug mode**, Active_flag of OTA_Partition is 1, which indicates that the code is ready for OTA process and there is no need to switch remote Active_Partition.

In this step, this document assumes that [Case 2](#) is used.

- Open a command line interface.
- Go to the flash_scripts folder.
- Type in ota_demo_sdk.bat (it may be changed or renamed), board (SDK board is used for the test, so type in **S**), and USB port name (**COM36**).

```
C:\k127\NXH3670_SDK_Gaming_G3.0\flash_scripts>ota_update_headset_ADZ96_20190511.bat
Updating an ADK[A] or SDK[S] board for headset? S
Enter USB port name of dongle: COM36
The USB port is COM36
Serial port COM36 opened
+++ reading layout file (C:\k127\NXH3670_SDK_Gaming_G3.0\flash_scripts\..\kinetis_democode\apps\kl_headset\script\layout
release_sdk_ADZ96_20190511.yml)...
##### flashing binaries ...
+++ reading flash list file ...
+++ checking flash list file ...
+++ connecting to the remote device ...
+++ getting remote table version ...
version: 48
--- skipping ssb image
+++ flashing kl_app @ index 0 ...
+++ calculating local fingerprint for index 0 ...
local fingerprint: 3517288705
+++ getting remote fingerprint for index 0 ...
remote fingerprint: 1995252804
@ [1]0 0x0 -> kinetis_democode/apps/kl_headset/sdk/release/4_1_led_blinky_2ABF0_eep.eep
[#####] 100%
--- skipping pairing_data image
--- skipping kl_ota_app image
--- skipping nxh_ota_app image
+++ changing remote active partition (1) ...
+++ rebooting remote to active partition ...
```

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4_1_led_blinky_2ABF0_eep.eep

ota_update_headset_ADZ96_20190511.bat
S
COM36
layout
release_sdk_ADZ96_20190511.yml
4_1_led_blinky_2ABF0_eep.eep

ota_update_headset_ADZ96_20190511.bat
S
COM36
layout
release_sdk_ADZ96_20190511.yml
4_1_led_blinky_2ABF0_eep.eep

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COM36
layout
release_sdk_ADZ96_20190511.yml
4_1_led_blinky_2ABF0_eep.eep

ota_update_headset_ADZ96_20190511.bat
S

```

k1_headset] WriteToPartition event (20 bytes @ id: 1 | offset: 0x11a8
k1_headset] WriteToPartition event (20 bytes @ id: 1 | offset: 0x11bc
k1_headset] WriteToPartition event (20 bytes @ id: 1 | offset: 0x11d0
k1_headset] WriteToPartition event (20 bytes @ id: 1 | offset: 0x11e4
k1_headset] WriteToPartition event (20 bytes @ id: 1 | offset: 0x11f8
k1_headset] WriteToPartition event (20 bytes @ id: 1 | offset: 0x120c
k1_headset] WriteToPartition event (20 bytes @ id: 1 | offset: 0x1220
k1_headset] WriteToPartition event (20 bytes @ id: 1 | offset: 0x1234

```

Figure 12. OTA_Headset WriteToPartition event

4 Software design

In order to describe the software design clearly, some programs are attached for user as reference.

4.1 Code of SSB

```

enum _vector_table_entries { kInitialSP = 0,kInitialPC };

uint32_t *appVectorTable = NULL;
uint32_t applicationAddress = 0;
uint32_t stackPointer = 0;

appVectorTable = (uint32_t *) (entry.startAddress + entry.imageOffsets[0] +
NVMMGR_EEP_INITIAL_HEADER_SIZE);
applicationAddress = appVectorTable[kInitialPC];
stackPointer = appVectorTable[kInitialSP];

JumpToApplication(applicationAddress, stackPointer);

```

...

```

void JumpToApplication(uint32_t applicationAddress, uint32_t stackPointer)
{
    /* Static variables are needed as we need to ensure the values we are using are not stored on the
previous stack */
    static uint32_t s_stackPointer = 0;
    s_stackPointer = stackPointer;
    static void (*farewellBootloader)(void) = 0;
    farewellBootloader = (void (*)(void))applicationAddress;

    /* Set the VTOR to the application vector table address */
    SCB->VTOR = applicationAddress;

    /* Set stack pointers to the application stack pointer */
    __set_MSP(s_stackPointer);
    __set_PSP(s_stackPointer);

    /* Jump to the application */
    farewellBootloader();
}

```

startup_LPC54114_cm4.s files can be modified to implement SSB feature.

```

bootValidApp    PROC
    EXPORT    bootValidApp
    LDR        r1, [r0, #0]    ; Get app stack pointer

```

```

MOV    sp,r1
LDR    r1, [r0, #4] ;
BX     r1           ; Get app reset vector
                     ; PC now point to App_Firmware
ENDP

```

4.2 Code of OTA receive

To let user understand the whole receive process of OTA easily, this section provides a event handler in the `OTA_Headset` code: `HCI_VS_WRITE_TO_PARTITION_SUB_EVENT` to introduce how to write firmware to Flash.

Assuming Dongle board is running **OTA_Dongle** demo and Headset board is running **OTA_Headset** demo, the NXH3670 of Headset can receive event from Dongle and transmit event to Host Controller (LPC54114) through the SPI interface.

1. The NXH3670 of Headset receives `HCI_VS_WRITE_TO_PARTITION_SUB_EVENT` (0Xe1) from the NXH3670 of Dongle and then runs `HCI_EvtWriteToPartitionHandler`.

```

{
    .evtCode = HCI_VS_EVENT_CODE,
    .subEvtCode = HCI_VS_WRITE_TO_PARTITION_SUB_EVENT,
    .evtHandler = HCI_EvtWriteToPartitionHandler,
    .evtParamsLen = HCI_UNDEFINED_PARAMETER_LENGTH,
},

```

2. The NXH3670 of Headset writes the data to the requested partition with offset. The following lists some APIs.

- To write outside of the current cached sector, copy all data in the current sector.

```
ReadFromFlash(s_Context.cacheBuf, SECTOR_SIZE_IN_BYTES, s_Context.cachedSectorAddr)
```

The sector size of LPC54114 is 32 KB, so a 32 KB cacheBuf is required to be defined in code design.

- Users can modify Cache with the data sent from NXH3670 of Dongle board.

```
memcpy(&s_Context.cacheBuf[cacheOffset], data, cpyLen);
```

- When the data of one packet is copied to cacheBuf, you can program Sector by using Flash write API.

```
ProgramSector(s_Context.cacheBuf, SECTOR_SIZE_IN_BYTES, s_Context.cachedSectorAddr);
```

3. The NXH3670 of Headset notifies that the operation is success to NXH3670 with a command.

```

HCI_CmdDataWritenToPartition(&req);
HCI_SendCmdBlocking(&req)

```

4.3 Code of OTA send

To let user understand the whole send process of OTA easily, this section uses Pseudo codes to introduce how **OTA_Dongle** sends firmware to **OTA_Headset**.

```

void UsbVcomDataReceived_Cb(uint32_t length, uint8_t *data)
{
    switch (opcode) {
        case HCI_CMD_VS_CONNECT_OPCODE: {
            ...
            HCI_CmdPrepareConnect(&hciReq, &connectParams);
            ...
            break;}
    }
}

```

```
default: {  
    ...  
    HCI_CmdPrepareHostGenericCmd(&hciReq, data, length);  
    ...  
    break;}  
}
```

NOTE

- **Case** HCI_CMD_VS_CONNECT_OPCODE

This command indicates that **OTA_Dongle** wants to connect **OTA_Headset**.

- **Default** CMD

OTA_Dongle will send any other command to **OTA_Headset** with. Actually, the MCU of **OTA_Headset** is responsible for writing these data to Flash.

5 Conclusions

With the Flashtool and files in **NXH3670_SDK_Gaming_G3.0**, you can update programs or make changes on your design needs. The firmware update speed via OTA is about 1 KB per second.

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